

Intro CENELEC TC 47X - Semiconductor devices and trusted chips

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CEN & CENELEC Stakeholder workshop 'Trusted Chips' – **Dec.2022**Main highlights: Trusted chips



Chips manufacturing has a **complex value chain** that relies on a **global supply chain**, involving **many actors**. There are different types of threats along the value chain that needs protection against.

Not all actors have the same requirements/knowledge of the security. A joint-up thinking is important. Standards can play a key role to improve the link between different actors and ensure the security at different step of the value chain.

Main highlight: Trusted Chips implementation



NEW Technical Committee : CLC/TC 47X for Semiconductor and Trusted Chips implementation



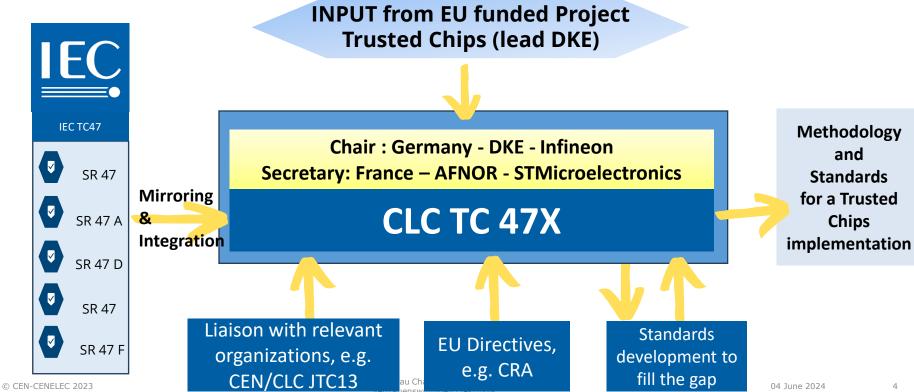
- ✓ Main focus : create hENs based on the CRA (Cyber Resilience Act)
- ✓ Support from additional EXPERTS is appreciated!

Objectives among others are:

- ✓ Secure and strengthen the chip manufacturing value chain, including cybersecurity, data safety and privacy
- ✓ Support Europe's competitiveness and resilience

Work program of TC47X





Outlook CENELEC TC47X



► Alignment with EU COM and CEN/CLC JTC13 SRAHG on the development of CRA standards for vertical semiconductor – ready by Oct. 2026

- Create further liaisons with expert organisations
- ▶ Alignment with DKE on EU COM project "Trusted Chips"
 - landscape of existing standards (semiconductors)
 - identify gaps and develop a related roadmap





TC47X - SEMICONDUCTORS AND TRUSTED CHIPS
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